

ABSTRACT

A thin-film deposition apparatus comprises a radio frequency power supply (D) configured to provide radio frequency power for generating an electric field in a processing chamber; a heating unit (100) including a heating tray (110) for heating a substrate (W) and a rotating shaft (120) supporting the heating tray (110); a support unit (200) including a support ring (210) disposed around the heating tray (110) and a support seat (230) supporting the support ring (210); a power transmission unit (300) fixedly connected to the rotating shaft (120); and a bearing portion (900) including a second bearing portion (920) and a third bearing portion (930), wherein the power transmission unit (300) is mounted on the third bearing portion (930), penetrates through the second bearing portion (920), and is fixedly connected to the rotating shaft (120); the support seat (230) is sleeved on the rotating shaft (120) and is fixedly connected to the second bearing portion (920), so that when the third bearing portion (930) moves up and down relative to the second bearing portion (920), the power transmission unit (300) and the heating unit (100) move up and down relative to the support unit (200), thereby solving the problem of poor uniformity of thin films deposited on the substrate (W) in the prior art.